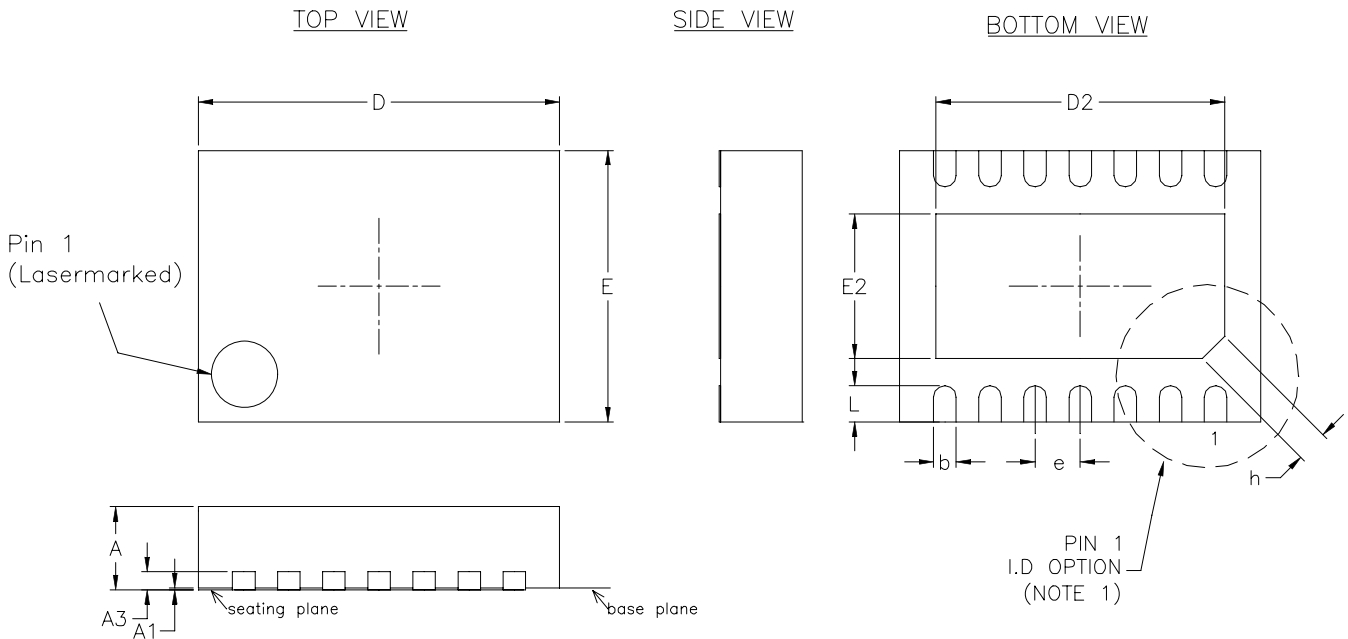


Date: 04.02.2013	PACKAGE OUTLINE SPECIFICATION	elmos[®] Services BV
Author: ASto	14 Lead Dual Flat Non Leaded Package (VDFN14L4030)	QM-No.: 08SP0647.03

Special leadframe, for this package is no variant within the JEDEC standard MO-229 E available.



Description	Symbol	mm			inch		
		min	typ	max	min	typ	max
Package height	A	0.80	0.90	1.00	0.031	0.035	0.039
Stand off	A1	0.00	0.02	0.05	0.000	0.00079	0.002
Thickness of terminal leads, including lead finish	A3	0.20 REF			0.0079 REF		
Width of terminal leads	b	0.18	0.25	0.30	0.0071	0.0098	0.012
Package length	D	4.00 BSC			0.157 BSC		
Package width	E	3.00 BSC			0.118 BSC		
Length of exposed pad	D2	3.10	3.20	3.30	0.122	0.126	0.130
Width of exposed pad	E2	1.50	1.60	1.70	0.059	0.063	0.067
Lead pitch	e	0.50 BSC			0.020 BSC		
Length of terminal for soldering to substrate	L	0.30	0.40	0.50	0.014	0.016	0.018
chamfer	h	0.35 BSC			0.014 BSC		
Number of terminal positions	N	14			14		

Note: the mm values are valid, the inch values contains rounding errors

Note 1: for assembler specific pin1 identification please see QM-document 08SP0363.xx (Pin 1 Specification)